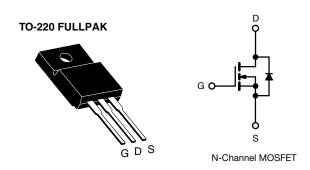
COMPLIANT

HALOGEN

FREE

Vishay Siliconix

E Series Power MOSFET



PRODUCT SUMMARY				
V _{DS} (V) at T _J max.	650)		
R _{DS(on)} max. (Ω) at 25 °C	V _{GS} = 10 V	0.6		
Q _g max. (nC)	40			
Q _{gs} (nC)	5			
Q _{gd} (nC)	9			
Configuration	Sing	le		

FEATURES

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (Ciss)
- · Reduced switching and conduction losses
- Ultra low gate charge (Qa)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

- · Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Renewable energy
 - Solar (PV inverters)

ORDERING INFORMATION	
Package	TO-220 FULLPAK
Lead (Pb)-free	SiHF7N60E-E3
Lead (Pb)-free and Halogen-free	SiHF7N60E-GE3

ABSOLUTE MAXIMUM RATINGS (T _C :	= 25 °C, unl	ess otherwis	se noted)		
PARAMETER			SYMBOL	LIMIT	UNIT
Drain Saurae Veltage			M	600	
Drain-Source Voltage $T_C = -25 ^{\circ}\text{C}, I_D = 250 \mu\text{A}$		V_{DS}	575	V	
Gate-Source Voltage			V_{GS}	± 30	
Continuous Proin Current (T. – 150 °C) 6	\/ at 10 \/	T _C = 25 °C	I-	7	
Continuous Drain Current ($T_J = 150 ^{\circ}\text{C}$) e V_{GS} at 10 V $T_C = 25 ^{\circ}\text{C}$ $T_C = 100 ^{\circ}\text{C}$		T _C = 100 °C	l _D	5	Α
Pulsed Drain Current ^a			I _{DM}	18	
Linear Derating Factor				0.25	W/°C
Single Pulse Avalanche Energy ^b			E _{AS}	43	mJ
Maximum Power Dissipation			P_{D}	31	W
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +150	°C
Drain-Source Voltage Slope $T_J = 125$ °C		dV/dt	70	V/ns	
Reverse Diode dV/dt ^d			3	V/IIS	
Soldering Recommendations (Peak temperature) ^c	Soldering Recommendations (Peak temperature) ^c For 10 s			300	°C
Mounting Torque M3 screw			0.6	Nm	

- a. Repetitive rating; pulse width limited by maximum junction temperature.
- b. $V_{DD} = 50 \text{ V}$, starting $T_J = 25 \text{ °C}$, L = 13.8 mH, $R_0 = 25 \Omega$, $I_{AS} = 2.5 \text{ A}$.
- c. 1.6 mm from case.
- d. $I_{SD} \le I_D$, $dI/dt = 100 \text{ A/}\mu\text{s}$, starting $T_J = 25 \,^{\circ}\text{C}$.
- e. Limited by maximum junction temperature.



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THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R_{thJA}	-	65	°C/W
Maximum Junction-to-Case (Drain)	R_{thJC}	-	4.0	C/VV

PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static							•
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} :	= 0 V, I _D = 250 μA	609	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C, I _D = 1 mA	-	0.68	-	V/°C
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μA	2	-	4	V
Cata Carriaga Lagliaga			$V_{GS} = \pm 20 \text{ V}$	-	-	± 100	nA
Gate-Source Leakage	I_{GSS}		$V_{GS} = \pm 30 \text{ V}$	-	-	± 1	μΑ
Zana Cata Valta da Busin Comunit	,	V _{DS} =	= 600 V, V _{GS} = 0 V	-	-	1	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 480 \	/, V _{GS} = 0 V, T _J = 125 °C	-	-	10	μA
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	$I_D = 3.5 A$	-	0.5	0.6	Ω
Forward Transconductance	9 _{fs}	V_{DS}	= 50 V, I _D = 3.5 A	-	1.9	-	S
Dynamic							
Input Capacitance	C _{iss}		$V_{GS} = 0 V$,		680	-	
Output Capacitance	C _{oss}	7	$V_{DS} = 100 \text{ V},$	-	39	-	1 !
Reverse Transfer Capacitance	C _{rss}	f = 1 MHz		-	5	-	pF
Effective Output Capacitance, Energy Related ^a	C _{o(er)}	V _{DS} = 0 V to 480 V, V _{GS} = 0 V		-	34	-	
Effective Output Capacitance, Time Related ^b	$C_{o(tr)}$	V _{DS} = 0 V	7 to 400 V, V _{GS} = 0 V	-	100	-	
Total Gate Charge	Qg			-	20	40	
Gate-Source Charge	Q _{gs}	V _{GS} = 10 V	$I_D = 3.5 A, V_{DS} = 480 V$	-	5	-	nC
Gate-Drain Charge	Q_{gd}			-	9	-	
Turn-On Delay Time	t _{d(on)}			-	13	26	
Rise Time	t _r	V _{DD} =	: 480 V, I _D = 3.5 A,	-	13	26	no
Turn-Off Delay Time	t _{d(off)}		= 10 V, $R_g = 9.1 \Omega$	-	24	48	ns
Fall Time	t _f		-	-	14	28	
Gate Input Resistance	R _g	f = 1	MHz, open drain	-	1.1	-	Ω
Drain-Source Body Diode Characteristic	S						
Continuous Source-Drain Diode Current	I _S	MOSFET sym showing the	bol	-	-	7	
Pulsed Diode Forward Current	I _{SM}	integral revers p - n junction	ブープ	-	-	18	A
Diode Forward Voltage	V _{SD}	T _J = 25 °C	C, I _S = 3.5 A, V _{GS} = 0 V	-	-	1.2	V
Reverse Recovery Time	t _{rr}	-		-	230	-	ns
Reverse Recovery Charge	Q _{rr}		$5 ^{\circ}\text{C}, I_{\text{F}} = I_{\text{S}} = 3.5 \text{A},$	-	1.9	-	μC
Reverse Recovery Current	I _{RRM}		100 A/ μ s, $V_R = 20 \text{ V}$	-	14	-	A

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} . b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

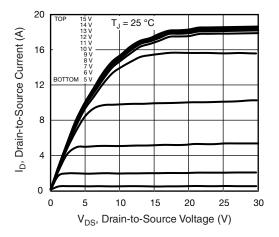


Fig. 1 - Typical Output Characteristics

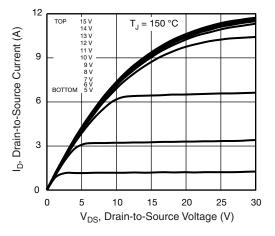


Fig. 2 - Typical Output Characteristics

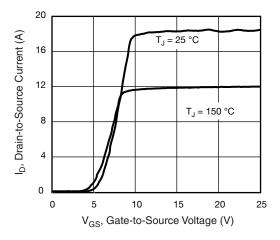


Fig. 3 - Typical Transfer Characteristics

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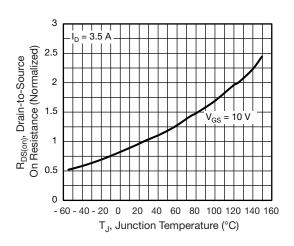


Fig. 4 - Normalized On-Resistance vs. Temperature

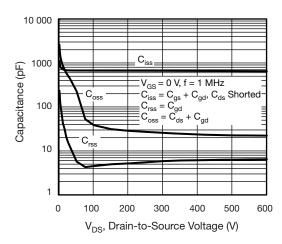


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

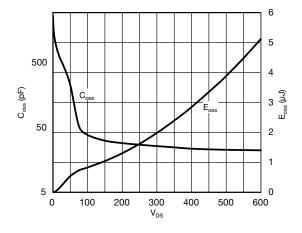


Fig. 6 - C_{oss} and E_{oss} vs. V_{DS}



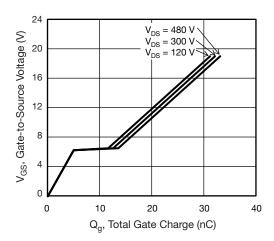


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

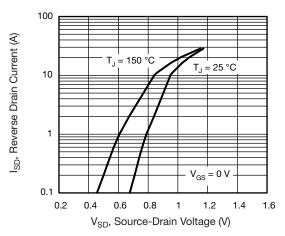


Fig. 8 - Typical Source-Drain Diode Forward Voltage

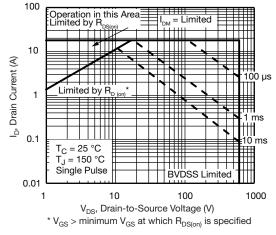


Fig. 9 - Maximum Safe Operating Area

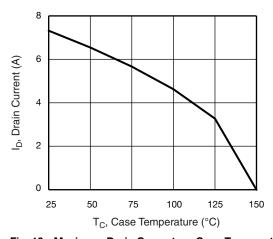


Fig. 10 - Maximum Drain Current vs. Case Temperature

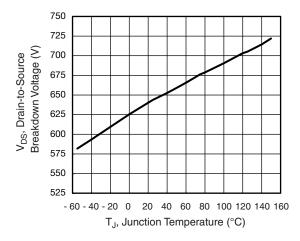


Fig. 11 - Temperature vs. Drain-to-Source Voltage



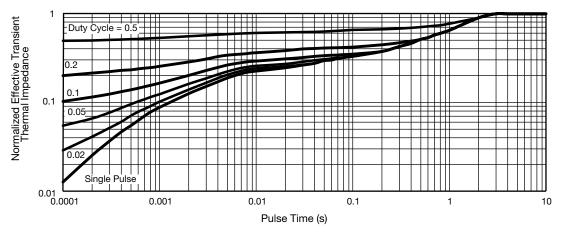


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

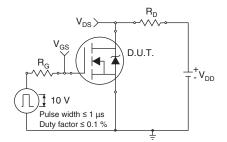


Fig. 13 - Switching Time Test Circuit

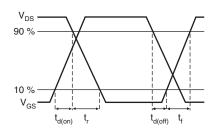


Fig. 14 - Switching Time Waveforms

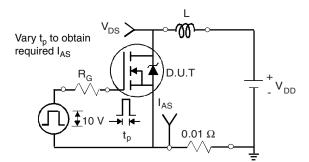


Fig. 15 - Unclamped Inductive Test Circuit

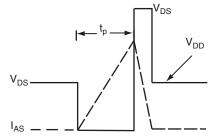


Fig. 16 - Unclamped Inductive Waveforms

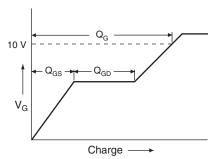


Fig. 17 - Basic Gate Charge Waveform

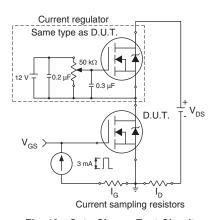
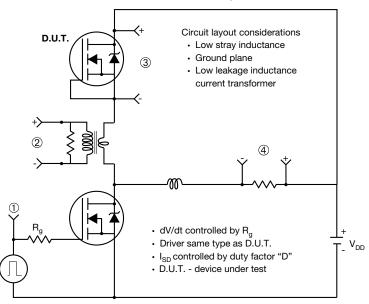


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



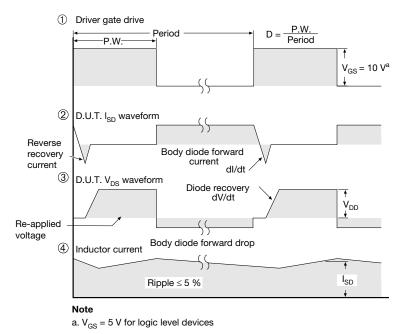


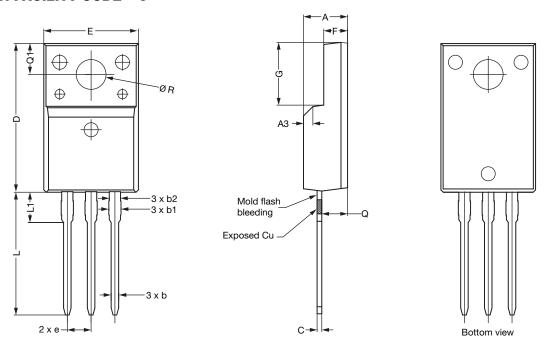
Fig. 19 - For N-Channel

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Vishay Siliconix

TO-220 FULLPAK (High Voltage)

OPTION 1: FACILITY CODE = 9

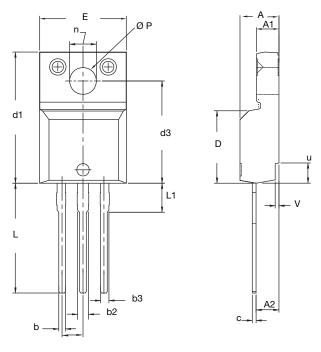


		MILLIMETERS	
DIM.	MIN.	NOM.	MAX.
Α	4.60	4.70	4.80
b	0.70	0.80	0.91
b1	1.20	1.30	1.47
b2	1.10	1.20	1.30
С	0.45	0.50	0.63
D	15.80	15.87	15.97
е		2.54 BSC	
E	10.00	10.10	10.30
F	2.44	2.54	2.64
G	6.50	6.70	6.90
L	12.90	13.10	13.30
L1	3.13	3.23	3.33
Q	2.65	2.75	2.85
Q1	3.20	3.30	3.40
ØR	3.08	3.18	3.28

- 1. To be used only for process drawing
- 2. These dimensions apply to all TO-220 FULLPAK leadframe versions 3 leads
- 3. All critical dimensions should C meet $C_{pk} > 1.33$
- 4. All dimensions include burrs and plating thickness
- 5. No chipping or package damage
- 6. Facility code will be the 1st character located at the 2nd row of the unit marking



OPTION 2: FACILITY CODE = Y



	MILLIM	MILLIMETERS INCHES		HES
DIM.	MIN.	MAX.	MIN.	MAX.
Α	4.570	4.830	0.180	0.190
A1	2.570	2.830	0.101	0.111
A2	2.510	2.850	0.099	0.112
b	0.622	0.890	0.024	0.035
b2	1.229	1.400	0.048	0.055
b3	1.229	1.400	0.048	0.055
С	0.440	0.629	0.017	0.025
D	8.650	9.800	0.341	0.386
d1	15.88	16.120	0.622	0.635
d3	12.300	12.920	0.484	0.509
Е	10.360	10.630	0.408	0.419
е	2.54	BSC	0.100 BSC	
L	13.200	13.730	0.520	0.541
L1	3.100	3.500	0.122	0.138
n	6.050	6.150	0.238	0.242
ØΡ	3.050	3.450	0.120	0.136
u	2.400	2.500	0.094	0.098
V	0.400	0.500	0.016	0.020

ECN: E19-0180-Rev. D, 08-Apr-2019 DWG: 5972

- 1. To be used only for process drawing
- 2. These dimensions apply to all TO-220 FULLPAK leadframe versions 3 leads
- 3. All critical dimensions should C meet $C_{pk} > 1.33$
- 4. All dimensions include burrs and plating thickness
- 5. No chipping or package damage
- 6. Facility code will be the 1st character located at the 2nd row of the unit marking



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Vishay

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